

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT7443351

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
CHENG-TA WU	09/21/2018
CHIA-SHIUNG TSAI	09/21/2018
JIECH-FUN LU	09/21/2018
KUAN-LIANG LIU	09/21/2018
SHIH-PEI CHOU	09/21/2018
YU-HUNG CHENG	09/21/2018
YEUR-LUEN TU	09/21/2018
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State/Country:	TAIWAN
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17869837
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Address Line 4:	CLEVELAND, OHIO 44114
ATTORNEY DOCKET NUMBER:	TSMCP892USB
NAME OF SUBMITTER:	MATTHEW W. GLAUSE
SIGNATURE:	/Matthew W. Glause/

PATENT

DATE SIGNED:	07/21/2022
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Total Attachments: 9

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PATENT ASSIGNMENT

PARTIES TO THE ASSIGNMENT

Assignor(s):
Cheng-Ta Wu

Assignor(s):
Chia-Shiung Tsai

Assignor(s):
Jiech-Fun Lu

Assignor(s):
Kuan-Liang Liu

Assignor(s):
Shih-Pei Chou

Assignor(s):
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Assignor(s):
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Assignee:
Taiwan Semiconductor Manufacturing Co., Ltd.
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Republic of China

AGREEMENT

WHEREAS, ASSIGNOR(S) (listed above) are inventor(s) of an invention entitled
"METHOD FOR FORMING A SEMICONDUCTOR-ON-INSULATOR (SOI) SUBSTRATE"
for which:

a non-provisional application for United States Letters Patent:

was executed on even date preparatory to filing (each inventor should sign this
Assignment on the same day as he/she signs the Declaration); or

was filed on _____ and accorded U.S. Serial No. _____; or

I hereby authorize and request my attorney associated with Customer No. 107476, to insert on the designated lines below the filing date and application number of said application when known:

U.S. Serial No. _____

filed on _____

WHEREAS, ASSIGNEE (listed above), a corporation of the Republic of China is desirous of acquiring the entire right, title and interest in and to the invention and in and to any letters patent that may be granted therefore in the United States and in any and all foreign countries;

NOW, THEREFORE, in exchange for good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNOR(S) hereby sell, assign and transfer unto ASSIGNEE its successors and assigns, the entire right, title and interest in and to said invention and improvements, said application and any and all letters patent which may be granted for said invention in the United States of America and its territorial possessions and in any and all foreign countries, and in any and all divisions, reissues, re-examinations and continuations thereof, including the right to file foreign applications directly in the name of ASSIGNEE and to claim priority rights deriving from said United States application to which said foreign applications are entitled by virtue of international convention, treaty or otherwise, said invention, application and all letters patent on said invention to be held and enjoyed by ASSIGNEE and its successors and assigns for their use and benefit and of their successors and assigns as fully and entirely as the same would have been held and enjoyed by ASSIGNOR(S) had this assignment, transfer and sale not been made. ASSIGNOR(S) hereby authorize and request the Commissioner of Patents and Trademarks to issue all letters patent on said invention to ASSIGNEE. ASSIGNOR(S) agree to execute all instruments and documents required for the making and prosecution of applications for

United States and foreign letters patent on said invention, for litigation regarding said letters patent, or for the purpose of protecting title to said invention or letters patent therefore.

2018.09.21
Date

cheng-Ta Wu
Name 1st Inventor Cheng-Ta Wu

2018/9/21
Date

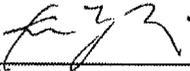
Chia-Shiung Tsai
Name 2nd Inventor Chia-Shiung Tsai

TSMC Docket No. P20173987US00
Docket No. TSMCP892US

2018/9/21
Date

Jiech-Fun Lu
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2018.9.21
Date


Name 4th Inventor Kuan-Liang Liu

TSMC Docket No. P20173987US00
Docket No. TSMCP892US

2018.9.21
Date

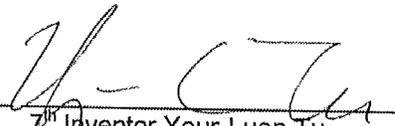
Shih-Pei Chou
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Date

Yu-Hung Cheng
Name 6th Inventor Yu-Hung Cheng

TSMC Docket No. P20173987US00
Docket No. TSMCP892US

2018/9/21
Date


Name Yeur-Luen Tu Inventor